

## WEST Search History

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DATE: Friday, October 27, 2006

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		<i>DB=PGPB; PLUR=YES; OP=ADJ</i>	
<input type="checkbox"/>	L6	(L3 and (drying fluid)and controlling).clm.	1
<input type="checkbox"/>	L5	L3 with (drying fluid)	5
<input type="checkbox"/>	L4	L3 with (first drying fluid)	0
<input type="checkbox"/>	L3	L2 with l1	6761
<input type="checkbox"/>	L2	semiconductor wafers	27708
<input type="checkbox"/>	L1	processing	553370

END OF SEARCH HISTORY

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**Search Results - Record(s) 1 through 1 of 1 returned.**☐ 1. Document ID: US 20050087211 A1

L6: Entry 1 of 1

File: PGPB

Apr 28, 2005

PGPUB-DOCUMENT-NUMBER: 20050087211

PGPUB-FILING-TYPE: new

DOCUMENT-IDENTIFIER: US 20050087211 A1

TITLE: System for rinsing and drying semiconductor substrates and method therefor

PUBLICATION-DATE: April 28, 2005

## INVENTOR-INFORMATION:

NAME	CITY	STATE	COUNTRY
Park, Ki Hwan	Suwon-Si		KR
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US-CL-CURRENT: 134/2; 134/172, 134/26

## ABSTRACT:

A system and method for cleaning and drying semiconductor wafers improves device yield by providing more advanced control of the ratio of drying fluid to cleaning fluid, for example the ratio of N.sub.2 vapor to IPA vapor. In addition, a quick drain process is employed to improve process throughput, and to further improve particle and watermark removal during the cleaning and drying steps.

Full	Title	Citation	Front	Review	Classification	Date	Reference	Sequences	Attachments	Claims	RMC	Draw De
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Term	Documents
DRYING	119177
DRYINGS	103

FLUID	223967
FLUIDS	88917
CONTROLLING	379167
CONTROLLINGS	9
(3 AND (DRYING ADJ FLUID) AND CONTROLLING).CLM..PGPB.	1
((L3 AND (DRYING FLUID)AND CONTROLLING).CLM.).PGPB.	1

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